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STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: Roy Knechtel and Andrej Lenz

Application No./Patent No.: 10/580,361 Filed/Issue Date: April 18, 2007

Entitled: PRODUCTION OF SEMICONDUCTOR SUBSTRATES WITH BURIED LAYERS
BY JOINING (BONDING) SEMICONDUCTOR WAFERS

X-FAB Semiconductor Foundries AG a corporation
(Name of Assignee) (Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest.
The extent (by percentage) of its ownership interest is _____ %

In the patent application/patent identified above by virtue of either:

A ☒ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.

OR

B ☐ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

1. From: _____ To: _____
The document was recorded in the United States Patent and Trademark Office at
Reel _____, Frame _____, or for which a copy thereof is attached.
2. From: _____ To: _____
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Reel _____, Frame _____, or for which a copy thereof is attached.
3. From: _____ To: _____
The document was recorded in the United States Patent and Trademark Office at
Reel _____, Frame _____, or for which a copy thereof is attached.

☐ Additional documents in the chain of title are listed on a supplemental sheet.

☐ Copies of assignments or other documents in the chain of title are attached.

[NOTE: A separate copy (i.e., a true copy of the original assignment document(s)) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.08]

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

Harald Mros
Signature

JUNE 13, 2006
Date

Harald Mros

Printed or Typed Name

Telephone Number

Corporate Lawyer

Title

This collection of information is required by 37 CFR 3.73(b). The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete the form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

COPY

Confirmatory assignment
in and before the USPTO

Dr. Roy KNECHTEL
Geraer Strasse 23
98716 Geraberg, Germany

and

Andrej LENZ
Burgschwaigerweg 17c
84529 Tittmoning, Germany

have invented

**Herstellung von Halbleitersubstraten mit vergrabenen
Schichten durch Verbinden von Halbleiterscheiben**
(Production of Semiconductor Substrates with buried Layers
by Joining (Bonding) Semiconductor Wafers)

for which PCT application PCT/DE2004/002638 was filed on the 29th day of November 2004 at RO = DE, now continued in USA as Serial No. 10/580,361 (Please insert when available).

The inventors have transferred said invention under German law of inventors, Section 9 ArbNErfG by way of "claiming" to and by the assignee, and by way of other separate agreement to

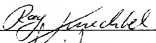
X-Fab Semiconductor Foundries AG
Haarbergstrasse 67
99097 Erfurt, Germany

The inventors have thereby acquired a right of monetary compensation under Sections 9, 12 ArbNErfG by virtue of German inventor law.


We do hereby authorize and request the Director of the United States Patent and Trademark Office to issue any and all letters patent which may be granted upon said United States applications, or upon said improvements or any parts thereof when granted, to said Assignee.

In Witness whereof we have hereunto set our hand and seal.

16. June 2006
Date


Dr. Roy KNECHTEL

12. June 2006
Date


Andrej LENZ